

(19)



JAPANESE PATENT OFFICE

PATENT ABSTRACTS OF JAPAN

(11) Publication number: **09316149 A**

(43) Date of publication of application: **09 . 12 . 97**

(51) Int. Cl  
**C08F299/02**  
**C08F290/06**  
**C08J 5/18**  
**G03F 7/027**  
**H01J 11/02**  
**H01J 17/49**

(21) Application number: **08159277**

(22) Date of filing: **31 . 05 . 96**

(71) Applicant: **NIPPON KAYAKU CO LTD**

(72) Inventor: **MORI SATORU**  
**YOKOSHIMA MINORU**

**(54) RESIN COMPOSITION, FILM THEREOF, AND CURED PRODUCT THEREOF**

(57) Abstract:

PROBLEM TO BE SOLVED: To provide a resin composition used for, e.g. a resistor pattern which can be developed with water or an aqueous alkali solution, having good precision, leaves little organic residues when baked by heating, and having excellent adhesion, a film thereof, and a cured product thereof.

SOLUTION: This composition contains a polymer (A) obtained by reacting a polymer prepared from a compound (a) having one (meth)acryloyl or vinyl group

and one glycidyl group in the molecule and an ethylenically unsaturated monomer copolymerizable with the compound (a) with an oligo- or poly-ethylene glycol (d) having an amino group at one terminal thereof and a compound (e) having one (meth)acryloyl or vinyl group and one carboxyl group in the molecule or a compound (A') obtained by allowing polymer A to enter into an addition reaction with a polycarboxylic anhydride, a diluent, a photopolymerization initiator, and at least one member selected among metal powder, metal oxides and glass.

COPYRIGHT: (C)1997,JPO